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(71) Applicant *(for all designated States except US)*: **LAM RESEARCH CORPORATION** [US/US]; 4650 Cushing Parkway, Fremont, California 94538 (US).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **DE LA LLERA, Anthony** [US/US]; 39420 Wilford Street, Fremont, California 94538 (US). **MANKIDY, Pratik** [IN/US]; 39547 Gallaudet Drive, Apt. 3011, Fremont, California 94538 (US). **KELLOGG, Michael C.** [US/US]; 5901 Marden Lane, Unit A, Oakland, California 94611 (US). **DHINDSA, Rajinder** [US/US]; 3670 Rollingside Drive, San Jose, California 95148 (US).

(74) Agent: **SKIFF, Peter K.**; BUCHANAN INGERSOLL & ROONEY PC, (Customer No. 21839), P. O. Box 1404, Alexandria, Virginia 22313-1404 (US).

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Declarations under Rule 4.17:

— *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*

— *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

[Continued on next page]

(54) **Title**: SHOWERHEAD ELECTRODE

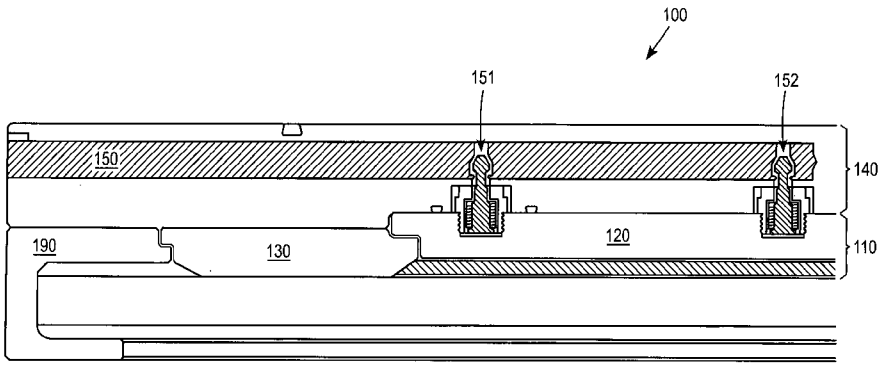


FIG. 1A

(57) **Abstract**: Abstract A showerhead electrode, a gasket set and an assembly thereof in plasma reaction chamber for etching semiconductor substrates are provided with improved a gas injection hole pattern, positioning accuracy and reduced warping, which leads to enhanced uniformity of plasma processing rate. A method of assembling the inner electrode and gasket set to a supporting member includes simultaneous engagement of cam locks.

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